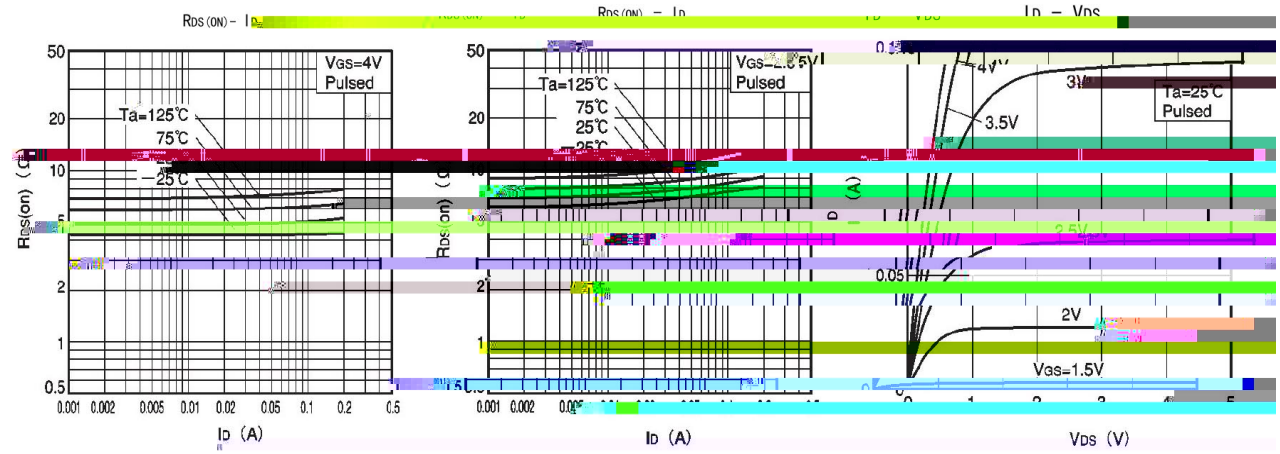
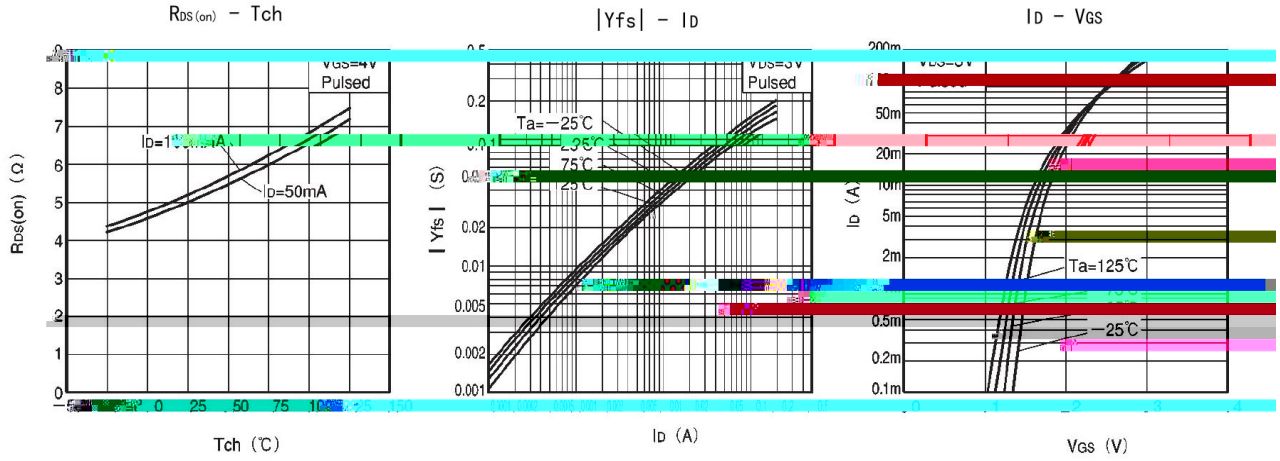
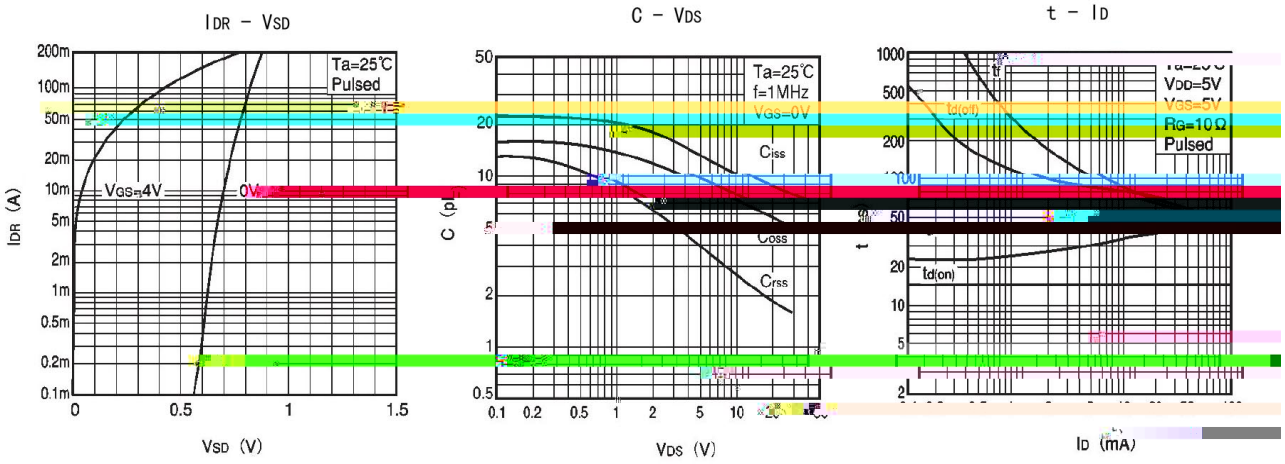
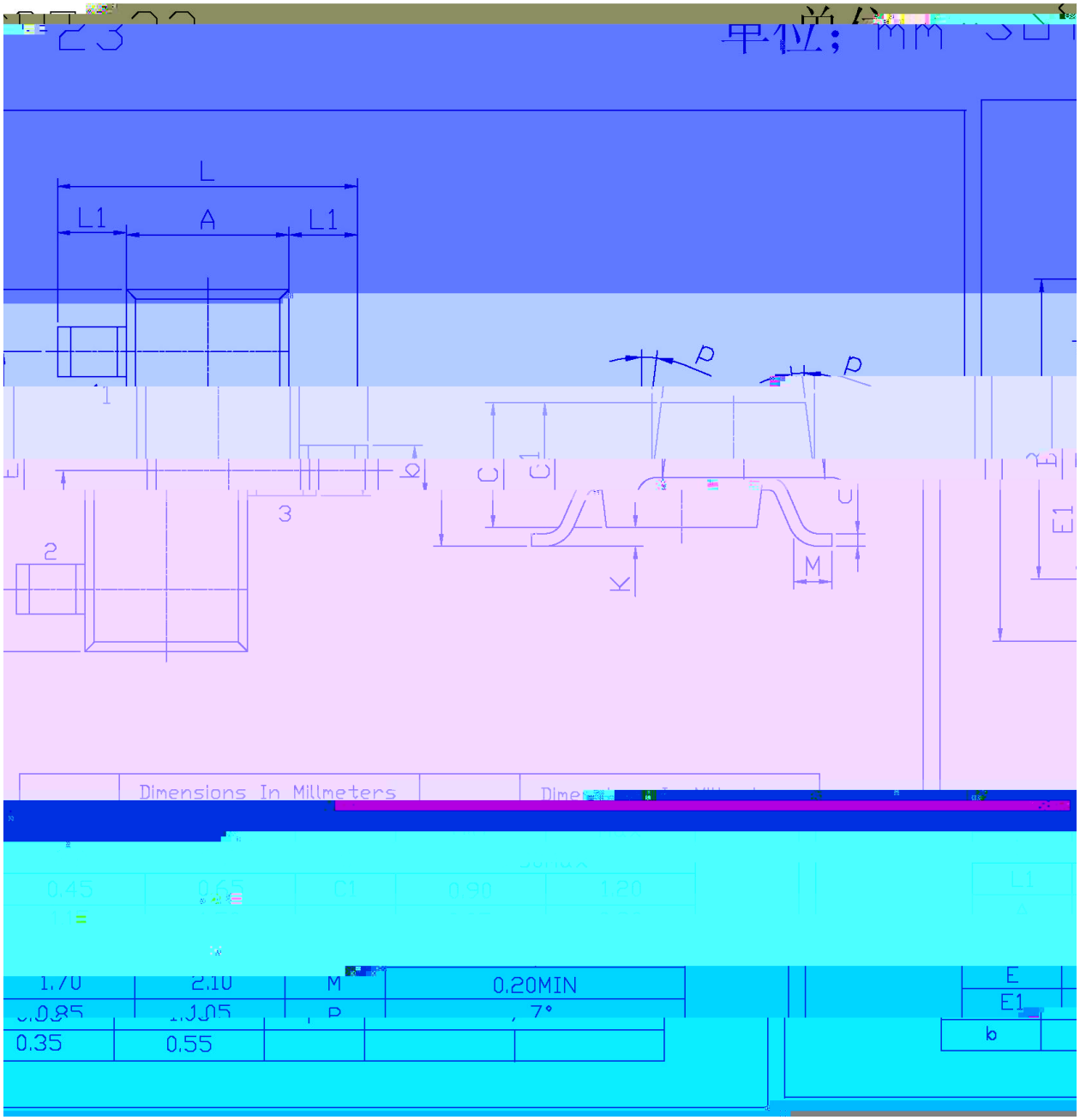
/ Electrical Characteristic Curve





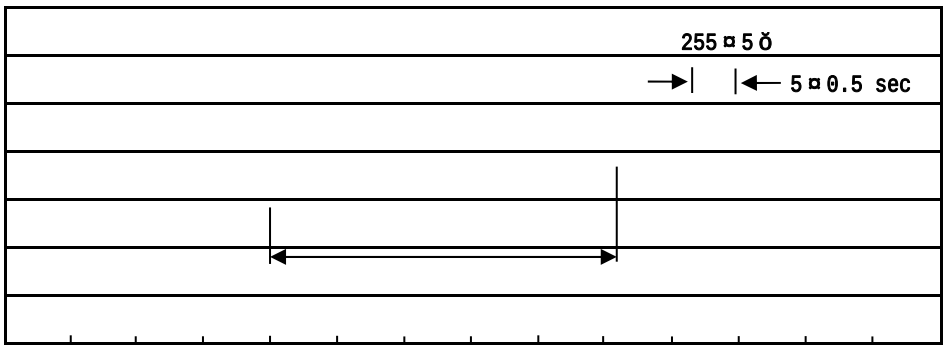


/ Package Dimensions



h / l n

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



ب χ				Note:
1	أ	150 200	ژ 60 120sec;	1.Preheating:150~200 , Time:60~120sec.
2		255±5	ژ ٨ 5±0.5sec;	2.Peak Temp.:255±5 , Duration:5±0.5sec.
3		٦ ھ	2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

χ 260±5	ژ χ 10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

` Ь / REEL

Package Type	Units					Dimension		(unit mm³)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices